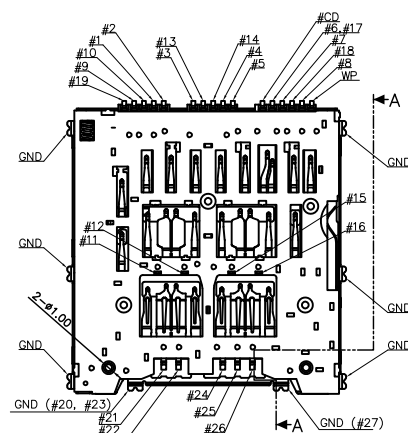
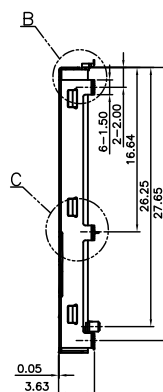
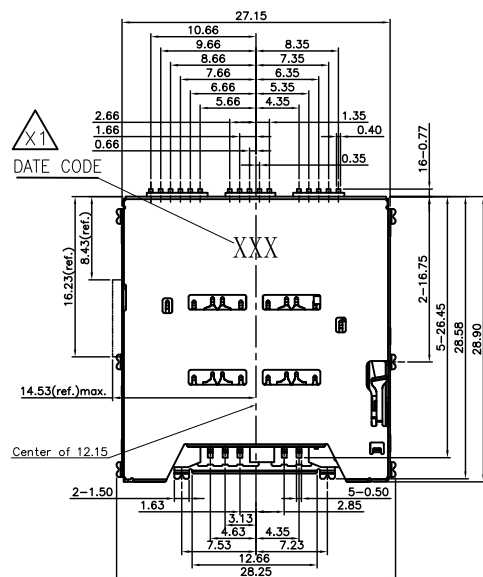




Section A-A

Date Code: 0 C Q

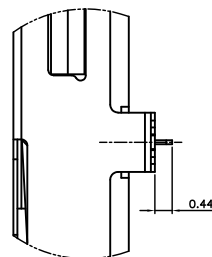
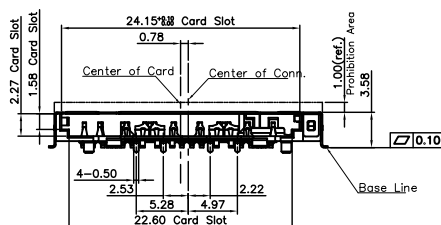
1. Material:
1-1 Housing:LCP 475, Color Black UL94-V0
1-2 Contact: Phosphor Bronze
1-3 Cover: SUS304-H

2.Plating:
2-1 Contact terminal:
Contact area: Gold 5u" Min.
Underplating: Ni overall 50U" Min. Solder area: Gold 5u" Min .
2-2 Cover:
Underplating: Solder Ni overall 50U" Min.

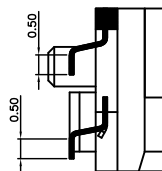
3. Specification:
3-1.Current Rating :0.5A max.
3-2.Contact Resistance: 50 mOhms max
3-3.Insulation Resistance:1000 MOhms min./500VDC
3-4.Dielectric Withstanding Voltage:500 V AC/1minute
3-5.Operating Temperature:-25°C to+85°C
3-6.Insertion force: 9.8N Max
3-7.Extraction force: 9.8N Max
3-8.Durability:10000 Cycles

4. Product Compliant to HALOGENFree+ RoHS2 Directive 2002/95/EC and ELV 2000/53/EC

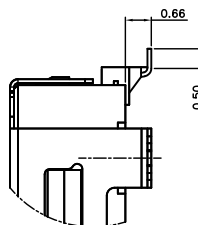
5. Recommending A Metal More Than 0.15mm Thick.
Please Confirm Solderability, If Use A Metal Mask Less Than 0.15mm Thick.



Detail C
Scale 4 : 1



Detail D
Scale 4 : 1



Detail B
Scale 4 : 1



深圳市华宇创精密电子有限公司

TOLERANCE:		DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME:	
X.X ±0.30	X.XX ±0.25			SD 8.0 PUSH SMT 3.58H	
X.XXX ±0.15		CHECKED BY: 马跃	DATE : 2014-02-23	PART NO.	HYCW99-SD29-358B
X.* ±2* X.X ±0.5*				MOLD NO.	
		APPROVED BY: 邱敏	DATE : 2014-02-23	DRAW NO:	HYC-2509011549
UNIT: mm [inch]				SHEET NO.	1 OF 1
SCALE:1:1	SIZE: A4				

A

1



d



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